



PK756 (v1.0) July 24, 2015

100% Material Declaration Data Sheet Spartan®-6 Cu Wire CP196 Package

Average Weight: 0.1350 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.007758	5.747%
	Silicon	7440-21-3	100.00	Main material	0.007758	
Die Attach Material					0.002083	1.543%
	Silver	7440-22-4	77.50	Main material	0.001614	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.000312	
	Acrylate monomer	Trade Secret	7.50	Main material	0.000156	
Copper Wire					0.000774	0.573%
	Cu	7440-50-8	98.25	Main material	0.000760	
	Pd	7440-05-3	1.75	Dopant	0.000014	
Mold Compound					0.062320	46.166%
	Epoxy Resin	Trade secret	7.50	Main material	0.004674	
	Phenol Resin A	9003-35-4	3.00	Main material	0.001870	
	Phenol Resin B	Trade secret	3.00	Main material	0.001870	
	Silica (Amorphous) A	60676-86-0	67.95	Filler	0.042346	
	Silica (Amorphous) B	7631-86-9	15.00	Filler	0.009348	
	Metal Hydroxide	Trade secret	3.00	Flame retardant	0.001870	
	Carbon black	1333-86-4	0.55	Color agent	0.000343	
Solder Balls					0.023319	17.274%
	Tin (Sn)	7440-31-5	63.00	Main material	0.014691	
	Lead (Pb)	7439-92-1	37.00	Main material	0.008628	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Substrate					0.038737	28.696%
	Au	7440-57-5	1.453	Main material	0.000563	
	Ni	7440-02-0	14.102	Main material	0.005463	
	Cu plating	7440-50-8	32.562	Plating	0.012613	
	Continuous Filament Fiber Glass	65997-17-3	11.105	Glass Fiber	0.004302	
	BT Core	26875-67-2 21645-51-2	33.316	Core	0.012906	
	Solder Mask	147-14-8 7727-43-7 14807-96-6 7631-86-9 112-15-2 34590-94-8 103429-90-9 64742-94-5 25551-13-7 trade secret	7.463	Solder mask	0.002891	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
7/24/15	1.0	Initial Xilinx release

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